

## Claims

1. An aromatic polycarbonate resin product for optical disc substrates, the product being produced by adding 0.015 to 0.05 parts by mass of a C<sub>14</sub>-C<sub>30</sub> fatty acid monoglyceride to 100 parts by mass of an aromatic polycarbonate resin, adding water having an electric conductivity, as measured at 25°C, of 1 μS/cm or less to the resin, the water content of the resin being controlled so as to fall within the range of 0.05 to 0.3 mass%, melt-extruding the water-added resin, cooling, and cutting to form pellets, the resin having a viscosity average molecular weight (Mv) of 10,000 to 20,000.

2. An aromatic polycarbonate resin product for optical disc substrates according to claim 1, wherein the melt-extruded aromatic polycarbonate resin is cooled by use of water having an electric conductivity, as measured at 25°C, of 1 μS/cm or less.

3. An aromatic polycarbonate resin product for optical disc substrates according to claim 1, wherein the aromatic polycarbonate resin has terminal groups in which p-cumylphenoxy group and/or p-tert-octylphenoxy group account for 30 mol% or more.

4. An aromatic polycarbonate resin product for optical disc substrates according to any of claims 1 to 3, wherein the aromatic polycarbonate resin has a viscosity average molecular weight (Mv) of 11,000 to 18,000.

5. An aromatic polycarbonate resin product for optical

disc substrates according to any of claims 1 to 3, wherein the aromatic polycarbonate resin has a viscosity average molecular weight (Mv) of 12,000 to 16,000.

6. An aromatic polycarbonate resin product for optical disc substrates according to any of claims 1 to 3, which contains a fatty acid monoglyceride in an amount of 0.02 to 0.04 parts by mass.

7. An aromatic polycarbonate resin product for optical disc substrates according to any of claims 1 to 3, wherein the fatty acid monoglyceride is stearic acid monoglyceride.

8. An aromatic polycarbonate resin product for optical disc substrates according to any of claims 1 to 3, wherein the water content of the resin is controlled so as to fall within the range of 0.05 to 0.2 mass%.